

Procedure file

Basic information		
DEA - Delegated acts procedure	2018/2947(DEA)	Procedure completed - delegated act enters into force
Exemption for lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages		
Supplementing 2008/0240(COD)		
Subject		
3.40.06 Electronics, electrotechnical industries, ICT, robotics		
3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)		

Key events			
16/11/2018	Non-legislative basic document published	C(2018)07499	
16/11/2018	Initial period for examining delegated act 2 month(s)		
28/11/2018	Committee referral announced in Parliament		
24/01/2019	Delegated act not objected by Parliament		